

B<sup>1</sup> optimal for the removal of an oxide film which does not have high selectivity and is small in thickness. This is however not always the case, and the conditions of this Comparative Example are still sufficient for the treatment in a step in which a large tolerance is permissible with respect to a loss.--

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IN THE CLAIMS

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Please amend Claim 1 as follows:

B<sup>2</sup> --1. (Twice amended) A process for cleaning a surface of a substrate, said surface carrying thereon a high-density film and a low-density film lower in density than said high-density film in combination, which comprises continuously bringing a mixed gas comprising anhydrous hydrogen fluoride gas and a heated inert gas into contact with said surface of said substrate such that at least a portion of said low-density film is removed without impairing said high-density film beyond a tolerance, wherein the mixed gas does not contain steam.

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✓ Please cancel Claim 4.

Please add the following new Claim 14:

B<sup>3</sup> 14. (New) A product obtained by the process according to Claim 1, wherein the high density film is a thermal oxide film, and is removed in an amount of 0 to not greater than 0.2 nm.--

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DISCUSSION OF THE AMENDMENT

The specification has been amended to correct a clerical error. Support for the amendment appears at page 29, lines 20-22.

Claim 1 has been amended to recite the mixed gas as --comprising-- the recited components, and that --the mixed gas does not contain steam--, as implicitly supported by